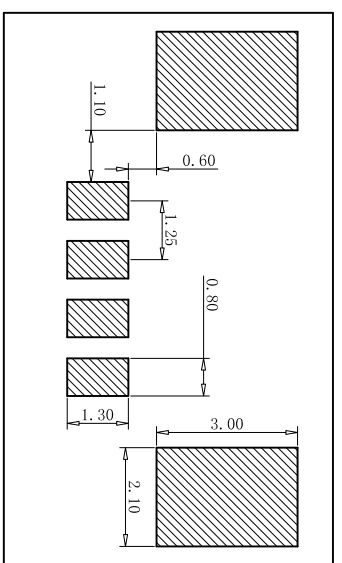
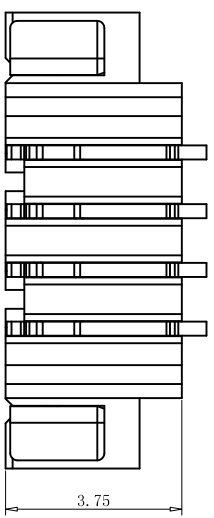
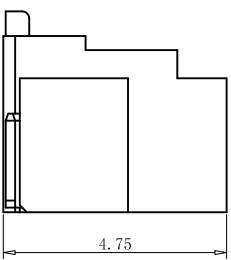
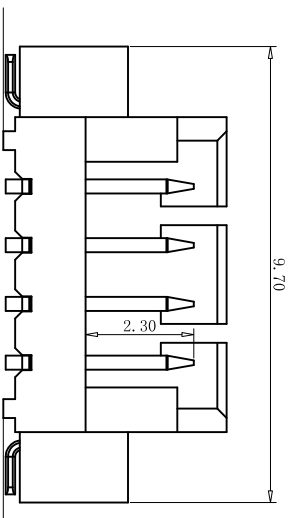
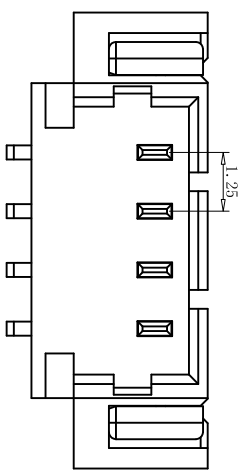


REV.	DESCRIPTION	APPD	DATE



NOTES:

1. MATERIAL:
HOUSING: HIGH TEMPERATURE THERMOPLASTIC
UL94V_0
CONTACT: COPPER ALLOYS.
COVER: COPPER ALLOYS OR STEEL.
2. PLATING:
UNDERPLATE: NICKEL.
3. MULTIMEDIA CARD COMPATIBLE

PART NO: WAF04-T1T1-2020-A		MATERIAL:	
LOT NO:		FINISH:	
UNIT: MM	SIZE: A4	COLOR:	
TOLERANCES: GENERAL: X, Y=±0.35 ANGLE: X, Y=±3.0° X, XX=±0.25 X, XY=±2.0° X, XXX=±0.15		TITLE: WAFER 1.25 立贴	
DR: 刘静	CHK: 刘静	DWG NO: FP-090012	REV: A
APP: 刘静	SCALE: 1:1	SHEET: 1 OF 1	

东莞市高敏达电子科技有限公司